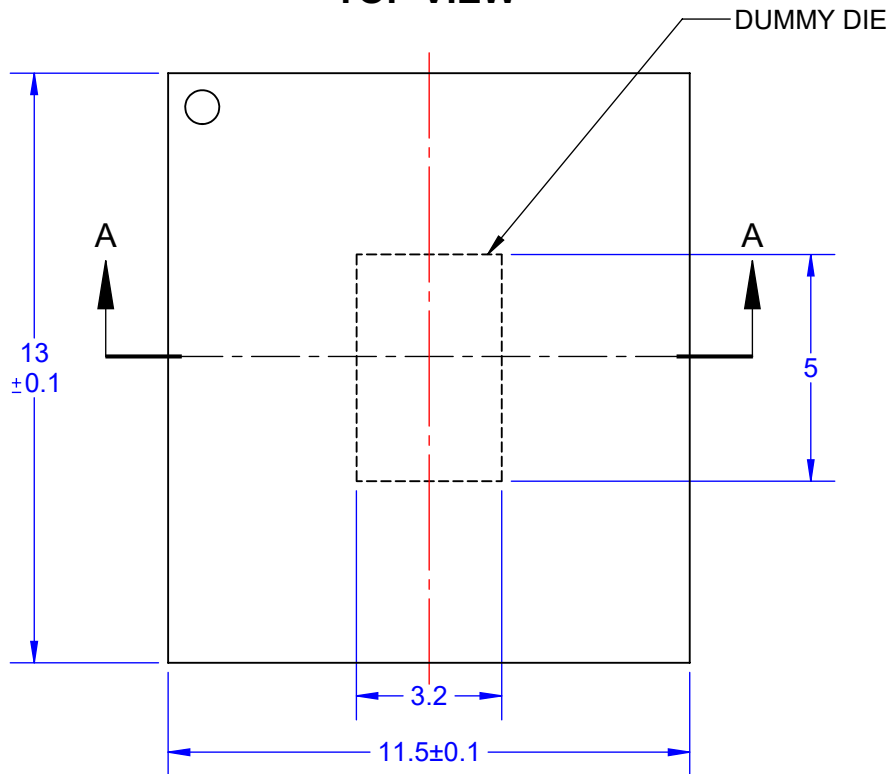
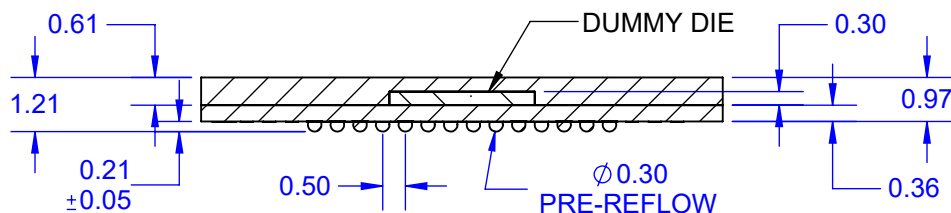
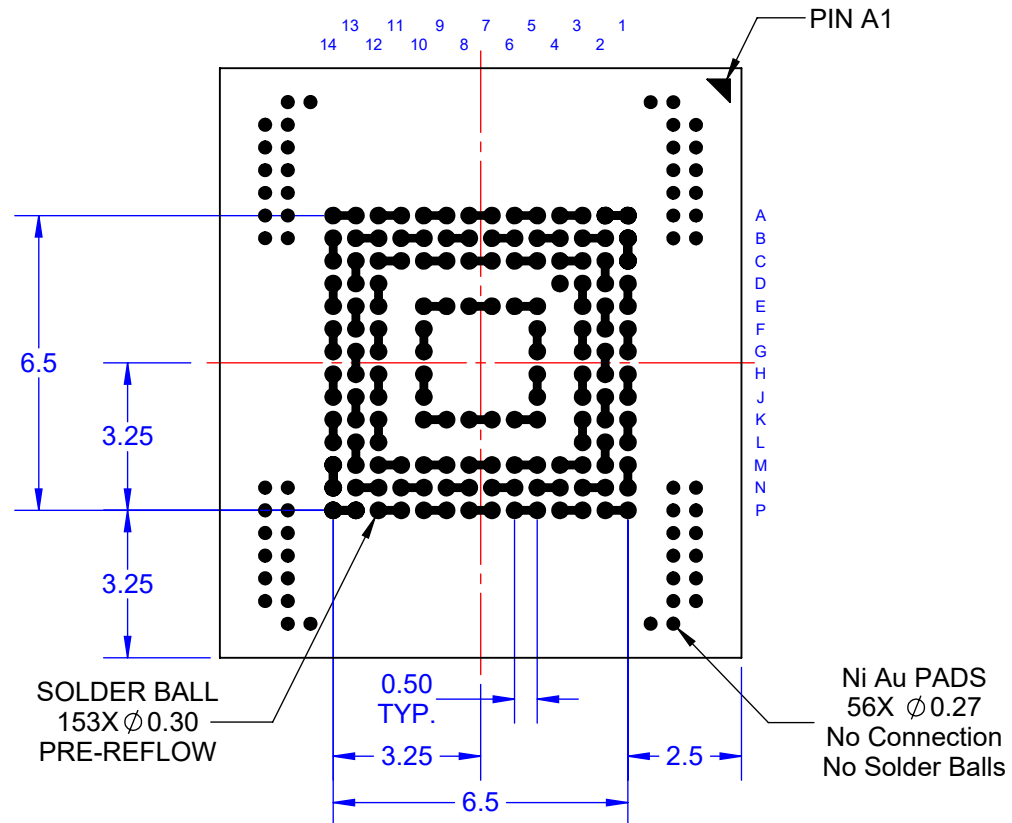


TOP VIEW



BALL VIEW



SECTION A-A
SCALE 6 : 1

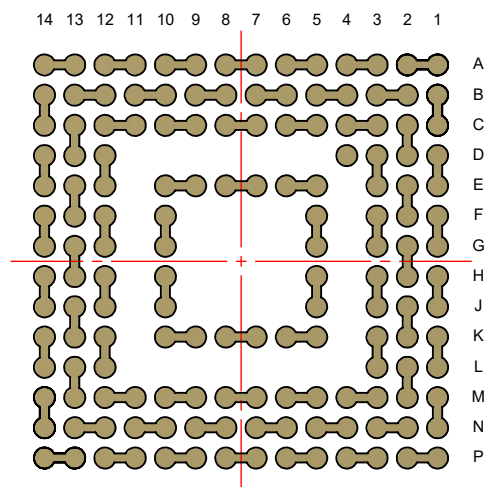
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.33mm (13.0 MIL).
- 5) PAD Cu DIAMETER: ~0.387mm (15.2 MIL) REF.
- 6) SUBSTRATE MATERIAL: BT
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN ATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

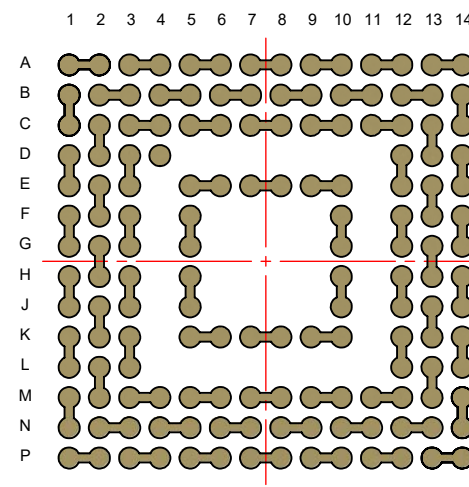
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA153T.5C-DC141D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA153T.5-DC141D	Sn63/Pb37	Sn63	NO	YES

APPROVALS	DATE				
DRAWN T. Au	7/11/2025				
ENG M. Hart	7/11/2025	TITLE BGA153T.5-DC141D DAISY CHAIN			
MFG					
QA		SCALE 6:1	SIZE A	DRAWING NO. 551413	REV C
CUST					
REVISED		DO NOT SCALE DRAWING			SHEET 1 OF 3

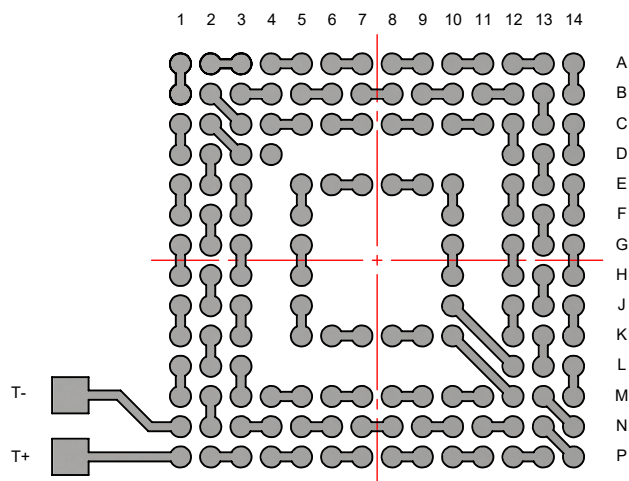
BALL VIEW



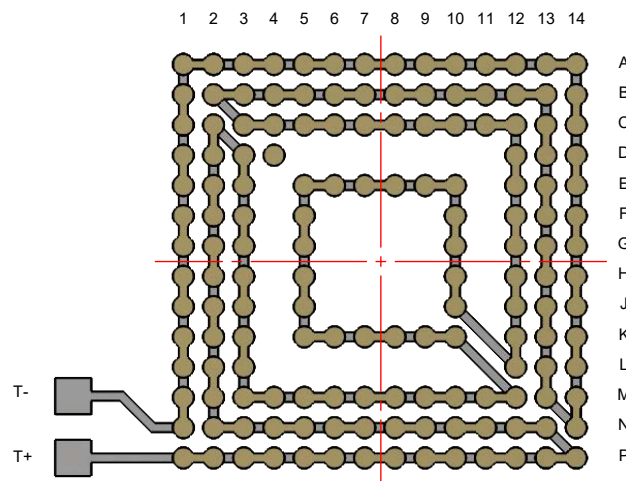
BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER ~0.387mm (15.2MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.33mm (13.0MIL).

TopLine®

TITLE BGA153T.5-DC141D
DAISY CHAIN

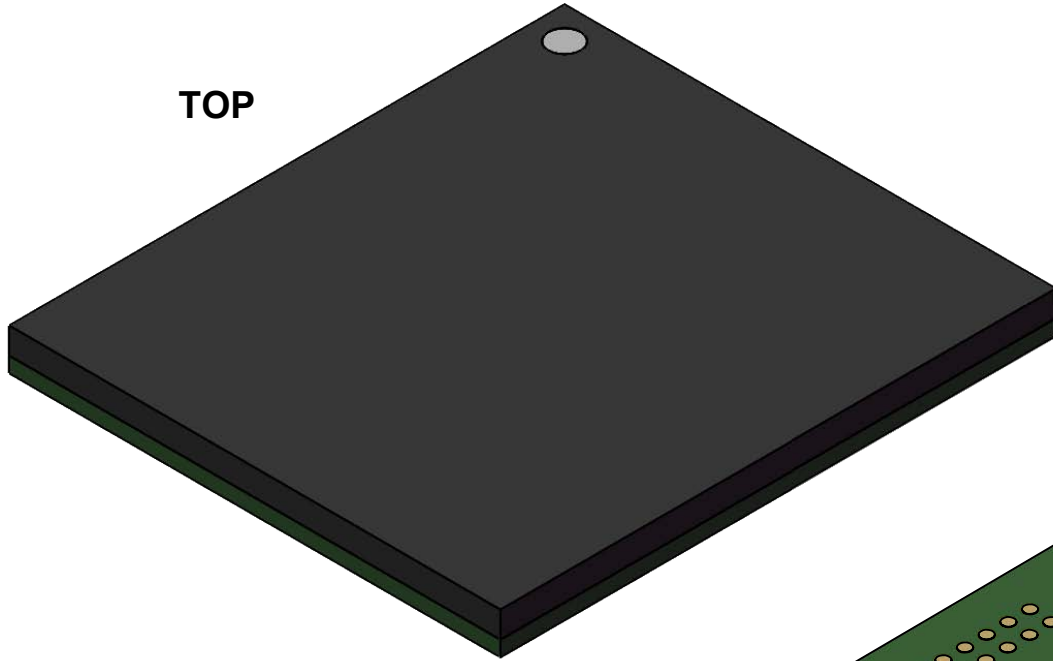
SCALE 8:1	SIZE A	DRAWING NO. 551413	REV C
--------------	-----------	-----------------------	----------

DO NOT SCALE DRAWING

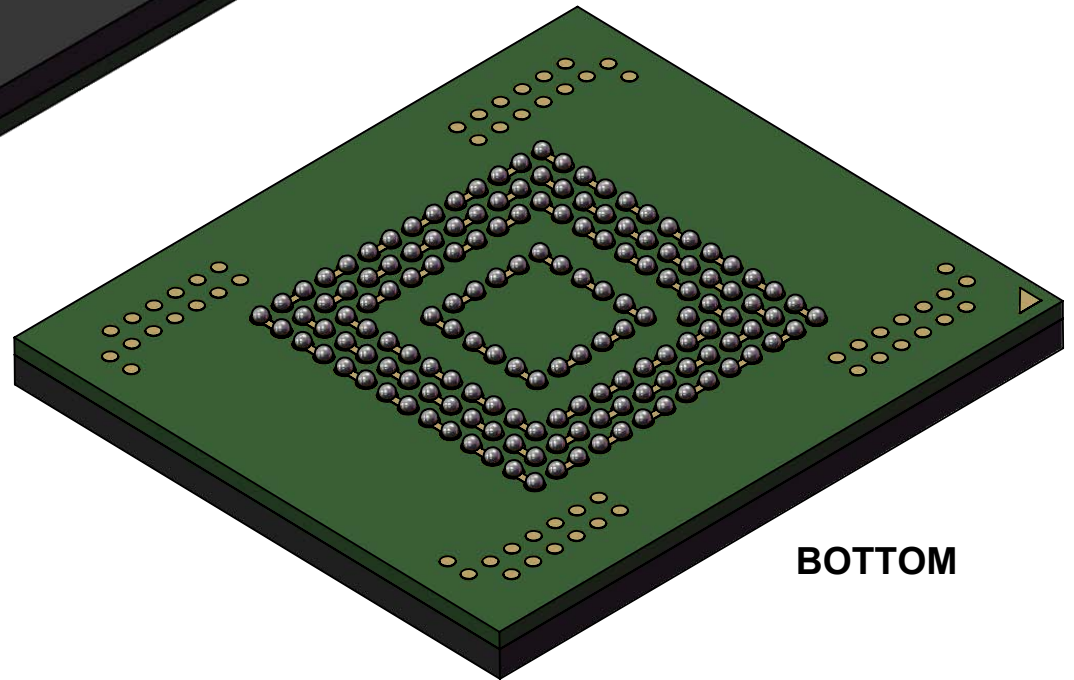
SHEET 2 OF 3

MODEL

TOP



BOTTOM



TopLine®

TITLE BGA153T.5-DC141D
DAISY CHAIN

SCALE 8:1	SIZE A	DRAWING NO. 551413	REV C
--------------	-----------	-----------------------	----------

DO NOT SCALE DRAWING

SHEET 3 OF 3